

Abstract**ELECTRONIC COMPONENT COMPRISING A MULTILAYER SUBSTRATE AND CORRESPONDING METHOD OF PRODUCTION**

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The invention provides a highly-integrated electronic component that consists of at least one chip component (CB), especially a filter operating with acoustic waves, and a multi-layer substrate, wherein the multi-layer substrate comprises integrated circuit elements for impedance transformation (IW) and additional integrated circuit elements, and serves as carrier substrate for chip components and discrete circuit elements (SE) disposed on their upper side. The component according to the invention makes it possible to implement multiple signal processing functions in one compact component, wherein especially the impedance of a chip component disposed on the multi-layer substrate is to be changed from a characteristic value to another predetermined value.

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Figure 1